L Number	Hits	Search Text	DB	Time stamp
-	0	soi and ((via hole open\$3 contact) with fox) and (thin\$4 with backside with	USPAT; US-PGPUB;	2003/10/09 14:40
		substrate) and (backside with (connection or contact))	EPO; JPO; DERWENT	
-	124		USPAT; US-PGPUB; EPO; JPO;	2003/10/09 15:06
-	75	(soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside	DERWENT USPAT; US-PGPUB;	2003/04/24 14:41
		with (connection or contact))) and @ad<19990423	EPO; JPO; DERWENT	14.41
-	69	soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:54
-	41	(soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:00
-	36	•	USPAT; US-PGPUB; EPO; JPO;	2003/10/09 15:09
_	25	((form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)) and @ad<19990423	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO;	2003/04/24 15:23
-	106	<pre>soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))</pre>	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
-	45	(soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:04
-	2559	<pre>((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
- 1	404	<pre>(((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:19
-	124	<pre>((((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08
-	26	(((((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:20
_	69	rear) adj side) ((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
_	0	((((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35

-	13		USPAT;	2003/10/08
		integration) and 438/\$3.ccls. and	US-PGPUB;	18:35
		@ad<19990423) and ((thin\$4 or remov\$3)	EPO; JPO;	
		with substrate) and soi	DERWENT	
-	136		USPAT;	2003/10/08
		and 438/\$3.ccls. and @ad<19990423	US-PGPUB;	18:34
			EPO; JPO;	
	_		DERWENT	/
-	0		USPAT;	2003/10/08
		integratable) and 438/\$3.ccls. and	US-PGPUB;	18:34
		@ad<19990423	EPO; JPO;	
			DERWENT	0000 (10 (00
-	3		USPAT;	2003/10/08 18:35
		integrat\$4) and 438/\$3.ccls. and	US-PGPUB; EPO; JPO;	10:35
		@ad<19990423) and ((back or rear) adj side)	DERWENT	
	0	· · · · · · · · · · · · · · · · · · ·	USPAT;	2003/10/08
-		integrat\$4) and 438/\$3.ccls. and	US-PGPUB;	18:36
		@ad<19990423) and ((back or rear) adj	EPO; JPO;	10.30
		side)) and ((thin\$4 or remov\$3) with	DERWENT	
1		substrate) and soi	55	
_	25		USPAT;	2003/10/08
	23	integrat\$4) and 438/\$3.ccls. and	US-PGPUB;	18:36
}		@ad<19990423) and ((thin\$4 or remov\$3)	EPO; JPO;	
		with substrate) and soi	DERWENT	
_	3347		USPAT;	2003/10/09
		or 438/672 or 438/675).ccls.	US-PGPUB;	14:41
			EPO; JPO;	
			DERWENT	
-	2559	((three adj dimensional) or	USPAT;	2003/10/09
	l	"three-dimensional") with ((integrated	US-PGPUB;	14:42
	1	adj circuit) or ic)	EPO; JPO;	
			DERWENT	0000/10/00
-	42		USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	14:42
		(((three adj dimensional) or	EPO; JPO;	
		"three-dimensional") with ((integrated	DERWENT	
ľ	24	adj circuit) or ic)) (((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
_	23	438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
		(((three adj dimensional) or	EPO; JPO;	
		"three-dimensional") with ((integrated	DERWENT	
		adj circuit) or ic))) and @ad<19990423		
-	134	soi and (via hole open\$3 contact) and	USPAT;	2003/10/09
		(thin\$4 with substrate) and (backside	US-PGPUB;	15:06
		with (connection or contact))	EPO; JPO;	
			DERWENT	
-	3	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:09
		(soi and (via hole open\$3 contact) and	EPO; JPO;	
		(thin\$4 with substrate) and (backside	DERWENT	
]	with (connection or contact)))	HCDATT.	2003/10/09
-	39	(form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside	USPAT; US-PGPUB;	15:09
		with (field adj oxide)) and (backside with etch\$3)	EPO; JPO;	13.05
		MICH ECCHAS!	DERWENT	
_	2	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:10
		((form\$3 with (via hole open\$3 contact)	EPO; JPO;	
		with (field adj oxide)) and (backside	DERWENT	
		with etch\$3))		
-	113		USPAT;	2003/10/09
		field and (substrate with (etch\$3 or	US-PGPUB;	15:10
		remov\$3))	EPO; JPO;	
			DERWENT	2002/10/22
_	10		USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB; EPO; JPO;	15:15
		(soi and (vertical with interconnect) and field and (substrate with (etch\$3 or	DERWENT	
		remov\$3)))	20.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	
	l	1	L	L

-	73	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
	ļ	438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
		((thin\$3 or remov\$3) with substrate) and	EPO; JPO;	
		soi	DERWENT	
-	28	(((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
	1	438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
	1	((thin\$3 or remov\$3) with substrate) and	EPO; JPO;	
		soi) and @ad<19990423	DERWENT	